

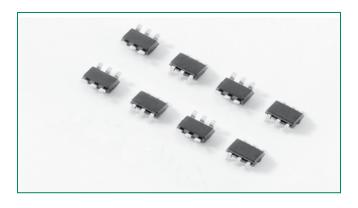
SP0504S Series 0.85pF Diode Array

AUTOMOTIVE GRADE

RoHS





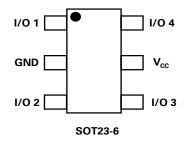


Description

Low Capacitance ESD Protection - SP0504S Series

The SP0504S integrates low capacitance rail-to-rail diodes with an integrated proprietary avalanche breakdown diode that protects applications against ESD, EFT and low surge events. This component is rated for the maximum IEC 61000-4-2 ESD (level 4) contact and air discharge events. Their very low off-state capacitance also makes them ideal for protecting high speed signal pins such as HDMI, DVI, USB2.0, and IEEE 1394.

Pinout

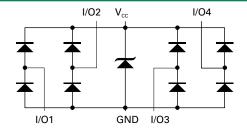


Features

- RoHS compliant and lead-free
- Low off-state capacitance of 0.85 pF (TYP) per I/O
- ESD rating of ±12kV contact discharge. ±15kV air discharge, (IEC 61000-4-2)
- EFT protection, IEC 61000-4-4, 40A

- (5/50ns)
- · Low leakage current of 0.5µA (MAX) at 5V
- Small packaging options saves board space
- Lightning, 4.5A (8/20µs as defined in IEC 61000-4-5 2nd edition)
- AEC-Q101 qualified

Functional Block Diagram



Applications

- · Computer Peripherals
- Mobile Phones
- PDA's
- Digital Cameras
- Network Hardware/Ports
- Test Equipment
- Medical Equipment
- Automotive Network

Additional Information

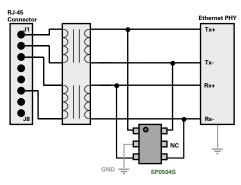






Samples

Application Example



A single 4 channel SP0504S component can be used to protect four of the data lines in a HDMI/DVI interface. Two (2) SP0504S components provide protection for the main data lines. Low voltage ASIC HDMI/DVI drivers can also be protected with the SP0504S, the $+V_{cc}$ pins on the SP0504S can be substituted with a suitable bypass capacitor or in some backdrive applications the $+V_{cc}$ of the SP0504S can be floated or NC.

Life Support Note:

Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

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TVS Diode Arrays (SPA®Diodes) Low Capacitance ESD Protection - SP0504S Series

| Absolute Maximum Ratings | | | | | |
|--------------------------|---------------------------------------|------------|-------|--|--|
| Symbol | Parameter | Value | Units | | |
| l _{PP} | Peak Current (t _p =8/20μs) | 4.5 | А | | |
| T _{OP} | Operating Temperature | -40 to 125 | °C | | |
| T _{STOR} | Storage Temperature | -55 to 150 | °C | | |

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

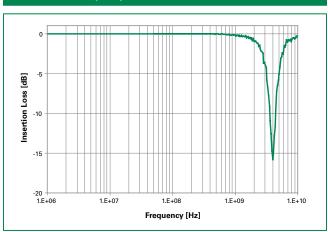
| Electrical Characteristics (T _{OP} =25°C) | | | | | | |
|--|----------------------|---|------|------|------|-------|
| Parameter | Symbol | Test Conditions | Min | Тур | Max | Units |
| Reverse Standoff Voltage | V _{RWM} | I _R = 1μA | - | - | 6.0 | V |
| Reverse Leakage Current | I _{LEAK} | V _R =5V | - | - | 0.5 | μΑ |
| Breakdown Voltage | V _{BR} | I _R =1mA | 6.3 | 8 | 8.8 | V |
| Clamp Voltage ¹ | V _c | I_{pp} =1A, t_{p} =8/20µs, I/O to GND | - | 9.5 | 11.0 | V |
| | | I_{pp} =2A, t_p =8/20µs, I/O to GND | - | 10.6 | 13.0 | V |
| ESD Withstand Voltage ¹ | V _{ESD} | IEC 61000-4-2 (Contact) | ±12 | - | - | kV |
| | | IEC 61000-4-2 (Air) | ±15 | - | - | kV |
| Diode Capacitance ¹ | C _{I/O-GND} | Reverse Bias=0V, f=1MHz | 0.95 | 1.1 | 1.25 | pF |
| | | Reverse Bias=1.65V, f=1MHz | 0.7 | 0.85 | 1.0 | pF |
| Diode Capacitance ¹ | C _{I/O-I/O} | Reverse Bias=0V, f=1MHz | - | 0.5 | - | pF |

Note: 1. Parameter is guaranteed by design and/or component characterization.

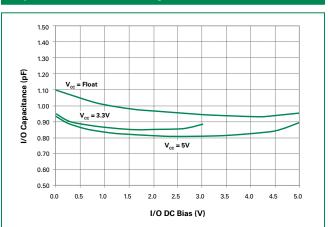
 $^{2.} Transmission\ Line\ Pulse\ (TLP)\ with\ 100 ns\ width,\ 2ns\ rise\ time,\ and\ average\ window\ t1=70 ns\ to\ t2=90 ns$



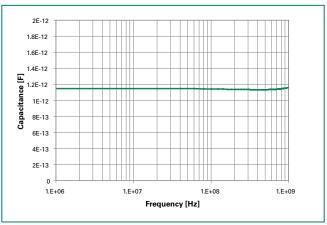
Insertion Loss (S21) I/O to GND



Capacitance vs. Bias Voltage



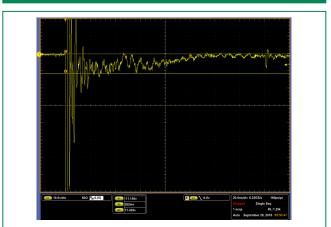
Capacitance vs. Frequency







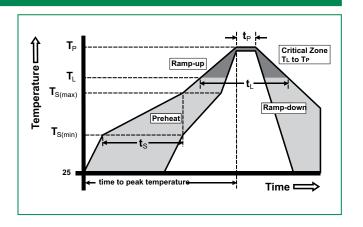
IEC 61000 -4-2 -8 kV Contact ESD Clamping Voltage



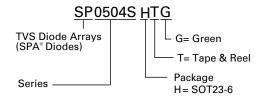


Soldering Parameters

| Reflow Condition | | Pb – Free assembly | |
|---|---|-------------------------|--|
| Pre Heat | - Temperature Min (T _{s(min)}) | 150°C | |
| | - Temperature Max (T _{s(max)}) | 200°C | |
| | -Time (min to max) (t _s) | 60 – 180 secs | |
| Average ra | amp up rate (Liquidus) Temp ak | 3°C/second max | |
| T _{S(max)} to T | ւ - Ramp-up Rate | 3°C/second max | |
| Reflow | - Temperature (T _L) (Liquidus) | 217°C | |
| | - Temperature (t _L) | 60 – 150 seconds | |
| Peak Temp | perature (T _P) | 260 ^{+0/-5} °C | |
| Time with | iin 5°C of actual peak ure (t _p) | 20 - 40 seconds | |
| Ramp-down Rate | | 6°C/second max | |
| Time 25°C to peak Temperature (T _p) | | 8 minutes Max. | |
| Do not ex | ceed | 260°C | |
| | | | |



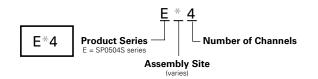
Part Numbering System



Product Characteristics

| Lead Plating | Matte Tin |
|---------------------|---|
| Lead Material | Copper Alloy |
| Lead Coplanarity | 0.0004 inches (0.102mm) |
| Substitute Material | Silicon |
| Body Material | Molded Compund |
| Flammability | UL Recognized compund meeting flammability rating V-0 |

Part Marking System

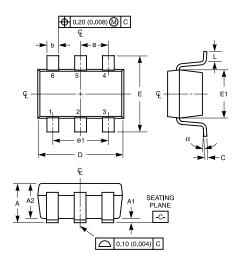


Ordering Information

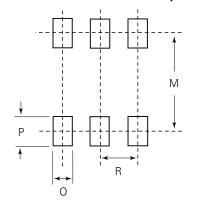
| Part Number | Package | Min. Order Qty. | | |
|-------------|---------|-----------------|--|--|
| SP0504SHTG | SOT23-6 | 3000 | | |



Package Dimensions — SOT23-6



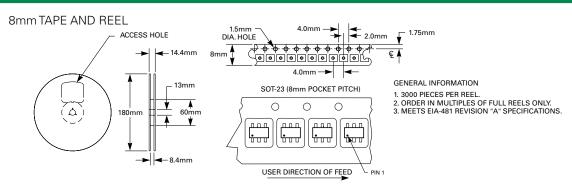
Recommended Solder Pad Layout



| Package | SOT23 | | | | | |
|---------|-------------|-------|------------|----------|-------|--|
| Pins | 6 | | | | | |
| JEDEC | MO-178AB | | | | | |
| | Millimeters | | Inches | | Notos | |
| | Min | Max | Min | Max | Notes | |
| Α | 0.900 | 1.450 | 0.035 | 0.057 | - | |
| A1 | 0.000 | 0.150 | 0.000 | 0.006 | - | |
| A2 | 0.900 | 1.300 | 0.035 | 0.051 | - | |
| b | 0.350 | 0.500 | 0.0138 | 0.0196 | - | |
| С | 0.080 | 0.220 | 0.0031 | 0.009 | - | |
| D | 2.800 | 3.000 | 0.11 | 0.118 | 3 | |
| E | 2.600 | 3.000 | 0.102 | 0.118 | - | |
| E1 | 1.500 | 1.750 | 0.06 | 0.069 | 3 | |
| е | 0.95 Ref | | 0.0374 ref | | - | |
| e1 | 1.9 Ref | | 0.074 | 8 Ref | - | |
| L | 0.30 | 0.600 | 0.012 | 0.023 | 4,5 | |
| N | 6 | | 6 | | 6 | |
| α | 0° | 8° | 0° | 8° | - | |
| М | | 2.590 | | 0.102 | - | |
| 0 | | 0.690 | | .027 TYP | - | |
| P | | 0.990 | | .039 TYP | - | |
| R | | 0.950 | | 0.038 | - | |

- Dimensioning and tolerancing Per ASME Y14.5M-1994 Package conforms to EIAJ SC-74 (1992).
- Dimensions D and E1 are exclusive of mold flash, protrusions, or gate burrs.
- Foot length L measured at reference to seating plane.
 "L" is the length of flat foot surface for soldering to substrate.
 "N" is the number of terminal positions.
- Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily

Embossed Carrier Tape & Reel Specification — SOT23-6



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